Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HPE FF 5950 32Q28 Swch(JH321A)
HPE FF 5950 32Q28 TAA Swch(JH322A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sqcm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardantsweighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

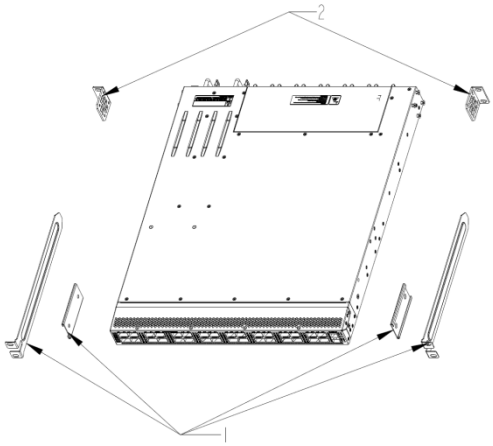
Tool Description	Tool Size (if applicable)
Screw driver	2#
Socket wrench	2.5#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 1, and then remove mounting angle 1.
2. Unscrew the screws on mounting angle 2, and then remove mounting angle 2.
3. Remove the fan-assembly 3.
4. Remove the power 4.
5. Remove the filler panel 5.
6. Unscrew the screws on top cover 6, and remove top cover 6.
7. Unscrew the screws on front panel 7, and then remove front panel 7.
8. Unscrew the screws on heat sink device 9
9. Unscrew the screws on plastic airguide 10,and then remove the plastic airguide 10
10. Unscrew the screws on PCB-assembly 11, and then remove PCB-assembly 11.
11. Remove all of the labels.
12. Unscrew the screws and hexagon posts on PCB 12, and then remove PCB 12.
13. Unscrew the screws on 13, and remove 13.
14. Unscrew the screws on PCB-assembly 14, and remove PCB-assembly 14.
15. Unscrew the screws on fan 3-1, and then remove fan 3-1.
16. Remove the fan snap rivets 3-2.
17. Remove the 3-3.
18. Remove the 3-4.
19. Unscrew the hexagon posts on PCB 11-1, and remove PCB 11-1.
20. Unscrew the screws on PCB 14-1, and remove PCB 14-1.
21. Remove all the shielding finger.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



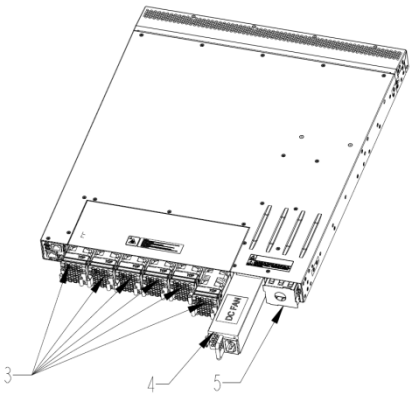
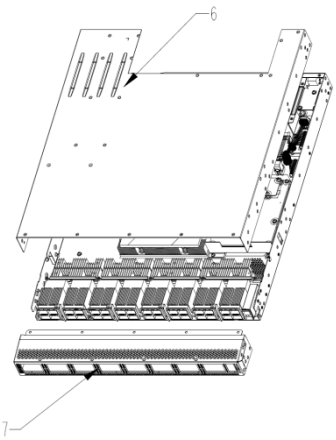


Figure 1Remove mounting angleFigure 2 Rear of the product



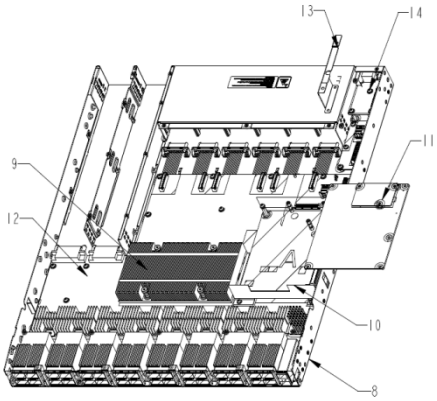
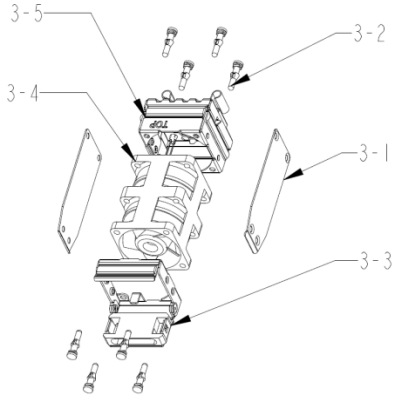


Figure 3Treatments to the productFigure 4Treatments to the product



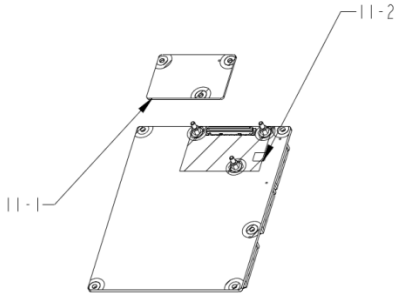


Figure 5 Treatments to fan-assembly 3Figure 6Treatments to PCB-assembly 11

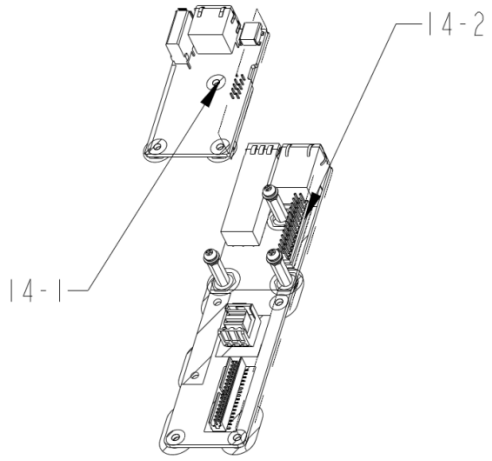


Figure 7Treatments to PCB-assembly 14

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	362	3.57%		Fe recycling
2		Fe	76	0.76%		Fe recycling
3						
	3-1	Fe	26	0.25%		Fe recycling
	3-2	PC	10	0.10%	Containing brominated flame retardants	
	3-3	Fe	25	0.25%		Fe recycling
	3-4	PC	100	0.99%	Containing brominated flame retardants	
	3-5	Fe	25	0.25%		Fe recycling
4		Fe	1050	10.43%		Fe recycling
5		Fe	20	0.20%		Fe recycling
6		Fe	1950	19.38%		Fe recycling
7		Fe	330	3.28%		Fe recycling
8		Fe	2650	26.33%		Fe recycling
9		Fe	400	3.97%		Fe recycling
10		PC	21	0.21%	Containing brominated flame retardants	
11						

	11-1	Complex PWB	10	0.10%	The surface of PCB is greater than 10 square centimeters;	
	11-2	Complex PWB	200	1.99%	The surface of PCB is greater than 10 square centimeters;	
12		Complex PWB	2700	26.83%	The surface of PCB is greater than 10 square centimeters;	
13		Fe	29	0.29%		Fe recycling
14						
	14-1	Complex PWB	20	0.20%	The surface of PCB is greater than 10 square centimeters;	
	14-2	Complex PWB	60	0.60%	The surface of PCB is greater than 10 square centimeters;	

4. Revised record

Date	Version	Author	Modify content
2016.03.17	V0	Zhou Hongjia	Initial version